

Abstract

Laser-Cutting Using Selective Polarization

A method of cutting a semiconductor wafer by selectively controlling and utilising the polarization of incident laser beam or beams, comprising irradiating the semiconductor wafer with laser light having a first polarization state, and subsequently irradiating the semiconductor wafer with laser light having a second polarization state, the second polarization state being different from the first polarization state.

(Figure 5)